

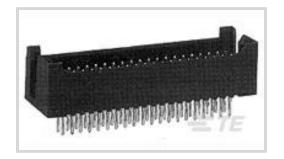
AMPMODU | AMPMODU Headers

TE Internal #: 5-534978-5 PCB Mount Header, Vertical, Board-to-Board, 30 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers

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PCB Connector Assembly Type: PCB Mount Header

PCB Mount Orientation: Vertical

Connector System: Board-to-Board

Number of Positions: **30**

Number of Rows: 2

Features

Product Type Features

PCB Connector Assembly Type

Connector System

Header Type

PCB Mount Header

Board-to-Board

Fully Shrouded

Printed Circuit Board

Configuration Features

Stackable	Yes
PCB Mount Orientation	Vertical
Number of Positions	30
Number of Rows	2
Board-to-Board Configuration	Parallel
Electrical Characteristics	
Termination Resistance	12 mΩ
Dielectric Withstanding Voltage (Max)	750 VAC
Operating Voltage	250 VAC
Body Features	
Primary Product Color	Black
Contact Features	
Mating Square Post Dimension	.64 mm[.025 in]

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	253 µin
Contact Layout	Inline
PCB Contact Termination Area Plating Material Finish	Matte
Contact Shape & Form	Square
PCB Contact Termination Area Plating Material	Tin
Contact Base Material	Phosphor Bronze
Contact Mating Area Plating Material	Gold
Contact Mating Area Plating Material Thickness	.762 μm[30 μin]
Contact Type	Pin
Contact Current Rating (Max)	3 A
Termination Features	
Square Termination Post & Tail Dimension	.64 mm[.025 in]
Termination Post & Tail Length	4.57 mm[.18 in]
Termination Method to Printed Circuit Board	Through Hole - Solder
Mechanical Attachment	
Mating Retention	Without
PCB Mount Retention Type	Retention Solder Tails
Mating Alignment	With
Mating Alignment Type	Guide Pins
PCB Mount Retention	With
PCB Mount Alignment	Without
Connector Mounting Type	Board Mount
Housing Features	
Centerline (Pitch)	2.54 mm[.1 in]
Housing Material	Thermoplastic
Dimensions	
Connector Height	5.03 mm
Row-to-Row Spacing	2.54 mm[.1 in]
Stack Height	11.43 mm[.45 in]
PCB Thickness (Recommended)	1.4 mm[.055 in]
Usage Conditions	
Operating Temperature Range	-65 – 105 °C[-85 – 221 °F]

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Operation/Application

Assembly Process Feature	None
Circuit Application	Signal
Industry Standards	
Approved Standards	CSA LE7189, UL E28476
UL Flammability Rating	UL 94V-0
Packaging Features	
Packaging Quantity	40
Packaging Type	Tube
Product Compliance	
For compliance documentation, visit the product page on TE.com>	
EU RoHS Directive 2011/65/EU	Compliant
EU ELV Directive 2000/53/EC	Compliant
China RoHS 2 Directive MIIT Order No 32, 2016	No Restricted Materials Above Threshold
EU REACH Regulation (EC) No. 1907/2006	Current ECHA Candidate List: JUNE 2023 (235) Candidate List Declared Against: JUNE 2023 (235)

Does not contain REACH SVHC

BFR/CFR/PVC Free, but Br/Cl >900 ppm in other sources.

Wave solder capable to 240°C

Halogen Content

Solder Process Capability

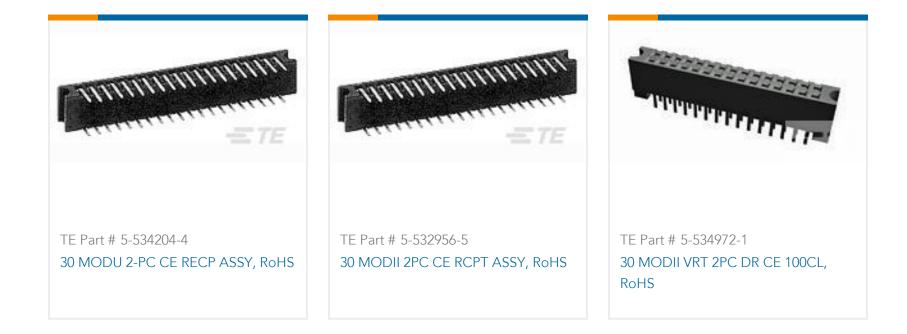
Product Compliance Disclaimer

This information is provided based on reasonable inquiry of our suppliers and represents our current actual knowledge based on the information they provided. This information is subject to change. The part numbers that TE has identified as EU RoHS compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, mercury, PBB, PBDE, DBP, BBP, DEHP, DIBP, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2011/65/EU (RoHS2). Finished electrical and electronic equipment products will be CE marked as required by Directive 2011/65/EU. Components may not be CE marked. Additionally, the part numbers that TE has identified as EU ELV compliant have a maximum concentration of 0.1% by weight in homogenous materials for lead, hexavalent chromium, and mercury, and 0.01% for cadmium, or qualify for an exemption to these limits as defined in the Annexes of Directive 2000/53/EC (ELV). Regarding the REACH Regulation, the information TE provides on SVHC in articles for this part number is based on the latest European Chemicals Agency (ECHA) 'Guidance on requirements for substances in articles' posted at this URL: https://echa.europa.eu/guidance-documents/guidance-on-reach

Compatible Parts

PCB Mount Header, Vertical, Board-to-Board, 30 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers





Also in the Series AMPMODU Headers





Wire-to-Board Connector Contacts(65)

Customers Also Bought



PCB Mount Header, Vertical, Board-to-Board, 30 Position, 2.54 mm [.1 in] Centerline, Fully Shrouded, Gold, Through Hole - Solder, AMPMODU Headers



Documents

Product Drawings 30 MODII 2PC HDR DR W/HLDWN, ROHS

English

CAD Files

Customer View Model ENG_CVM_CVM_5-534978-5_S.2d_dxf.zip

English

3D PDF

3D

Customer View Model

ENG_CVM_CVM_5-534978-5_S.3d_igs.zip

English

Customer View Model

ENG_CVM_CVM_5-534978-5_S.3d_stp.zip

English

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Datasheets & Catalog Pages AMPMODU_INTERCONNECTION_SYSTEM_SECTION5_CONT

English